

2N6394 Series

Silicon Controlled Rectifiers Reverse Blocking Thyristors

Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supplies.

Features

- Glass Passivated Junctions with Center Gate Geometry for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Blocking Voltage to 800 V
- These are Pb-Free Devices

MAXIMUM RATINGS[†] (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) (T _J = -40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open)	V _{DRM} , V _{RRM}	50 100 400 800	V
On-State RMS Current (180° Conduction Angles; T _C = 90°C)	I _{T(RMS)}	12	A
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave, 60 Hz, T _J = 90°C)	I _{TSM}	100	A
Circuit Fusing (t = 8.3 ms)	I ² t	40	A ² s
Forward Peak Gate Power (Pulse Width ≤ 1.0 μs, T _C = 90°C)	P _{GM}	20	W
Forward Average Gate Power (t = 8.3 ms, T _C = 90°C)	P _{G(AV)}	0.5	W
Forward Peak Gate Current (Pulse Width ≤ 1.0 μs, T _C = 90°C)	I _{GM}	2.0	A
Operating Junction Temperature Range	T _J	-40 to +125	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

MAXIMUM RATINGS[†] (T_J = 25°C unless otherwise noted)

Rating	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	R _{θJC}	2.0	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	T _L	260	°C

[†]Indicates JEDEC Registered Data

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.



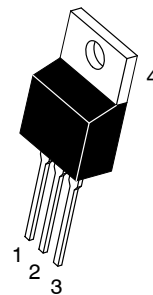
ON Semiconductor[®]

<http://onsemi.com>

SCRs
12 AMPERES RMS
50 thru 800 VOLTS



MARKING DIAGRAM



TO-220AB
CASE 221A
STYLE 3



2N639x = Device Code
x = 4, 5, 7, or 9
G = Pb-Free Package
A = Assembly Location
Y = Year
WW = Work Week

PIN ASSIGNMENT

Pin	Assignment
1	Cathode
2	Anode
3	Gate
4	Anode

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

2N6394 Series

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

†Peak Repetitive Forward or Reverse Blocking Current (V _{AK} = Rated V _{DRM} or V _{RDM} , Gate Open)	I _{DRM} , I _{RDM}	T _J = 25°C	-	-	10	μA
		T _J = 125°C	-	-	2.0	mA

ON CHARACTERISTICS

†Peak Forward On-State Voltage (Note 2) (I _{TM} = 24 A Peak)	V _{TM}	-	1.7	2.2	V
†Gate Trigger Current (Continuous dc) (V _D = 12 Vdc, R _L = 100 Ohms)	I _{GT}	-	5.0	30	mA
†Gate Trigger Voltage (Continuous dc) (V _D = 12 Vdc, R _L = 100 Ohms)	V _{GT}	-	0.7	1.5	V
Gate Non-Trigger Voltage (V _D = 12 Vdc, R _L = 100 Ohms, T _J = 125°C)	V _{GD}	0.2	-	-	V
†Holding Current (V _D = 12 Vdc, Initiating Current = 200 mA, Gate Open)	I _H	-	6.0	50	mA
Turn-On Time (I _{TM} = 12 A, I _{GT} = 40 mAdc, V _D = Rated V _{DRM})	t _{gt}	-	1.0	2.0	μs
Turn-Off Time (V _D = Rated V _{DRM})	t _q	(I _{TM} = 12 A, I _R = 12 A) (I _{TM} = 12 A, I _R = 12 A, T _J = 125°C)	-	15 35	- μs

DYNAMIC CHARACTERISTICS

Critical Rate-of-Rise of Off-State Voltage Exponential (V _D = Rated V _{DRM} , T _J = 125°C)	dv/dt	-	50	-	V/μs
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†Indicates JEDEC Registered Data

2. Pulse Test: Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

Voltage Current Characteristic of SCR

Symbol	Parameter
V _{DRM}	Peak Repetitive Off State Forward Voltage
I _{DRM}	Peak Forward Blocking Current
V _{RDM}	Peak Repetitive Off State Reverse Voltage
I _{RDM}	Peak Reverse Blocking Current
V _{TM}	Peak On State Voltage
I _H	Holding Current

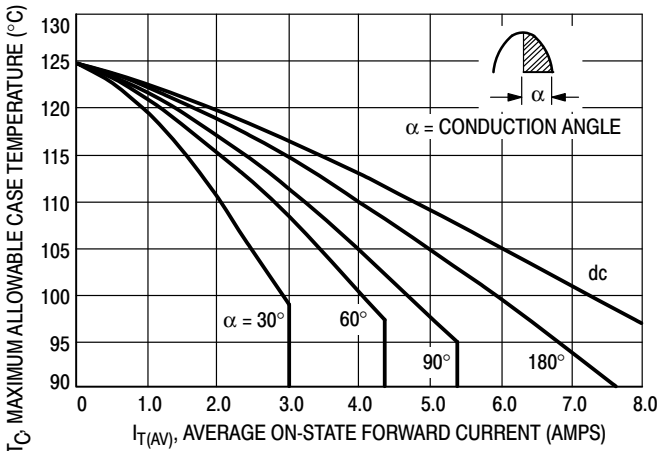
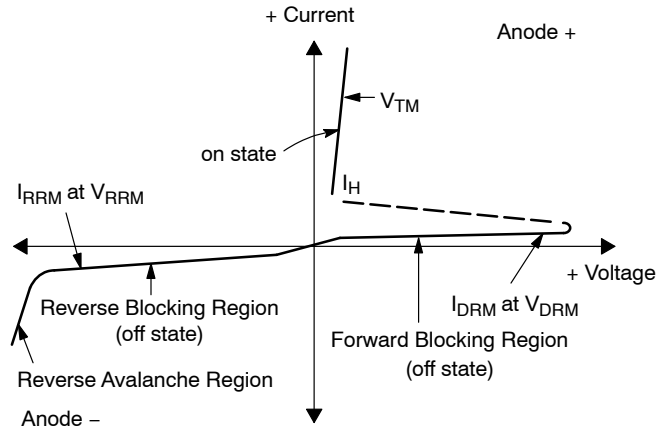


Figure 1. Current Derating

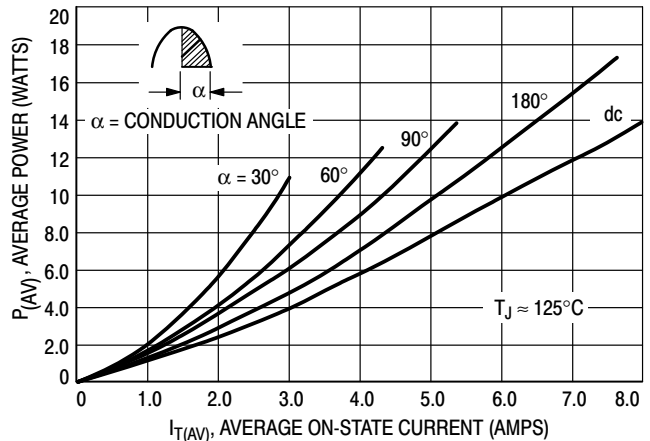


Figure 2. Maximum On-State Power Dissipation

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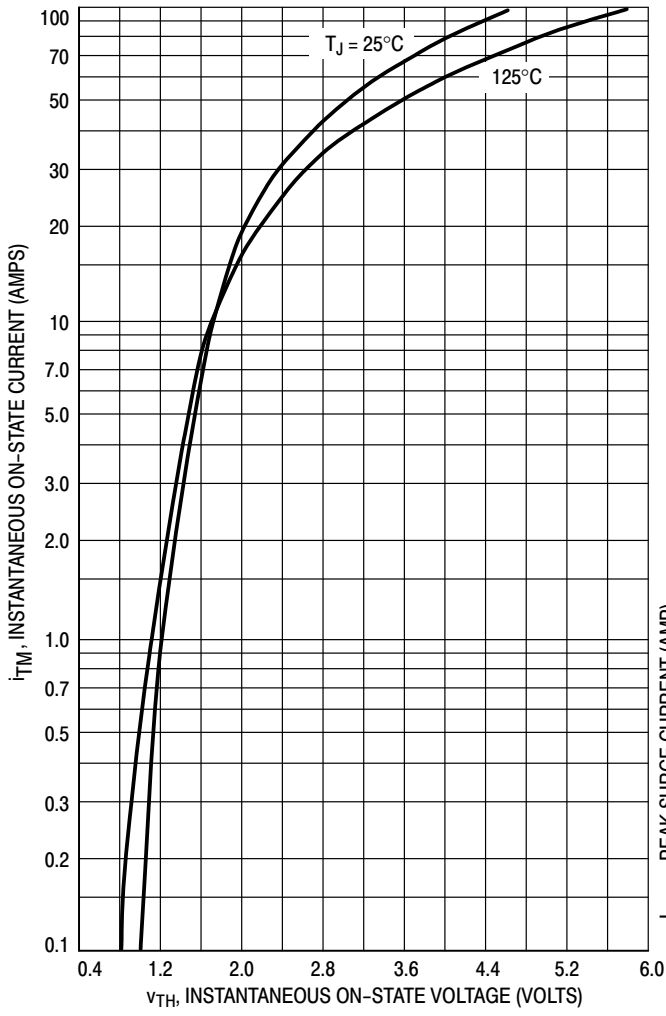


Figure 3. On-State Characteristics

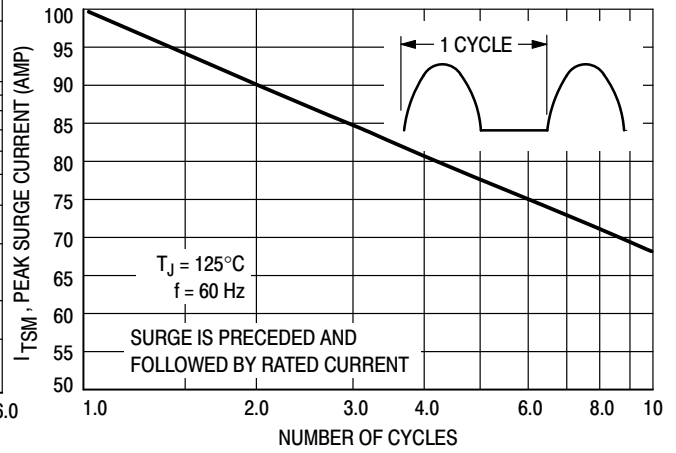


Figure 4. Maximum Non-Repetitive Surge Current

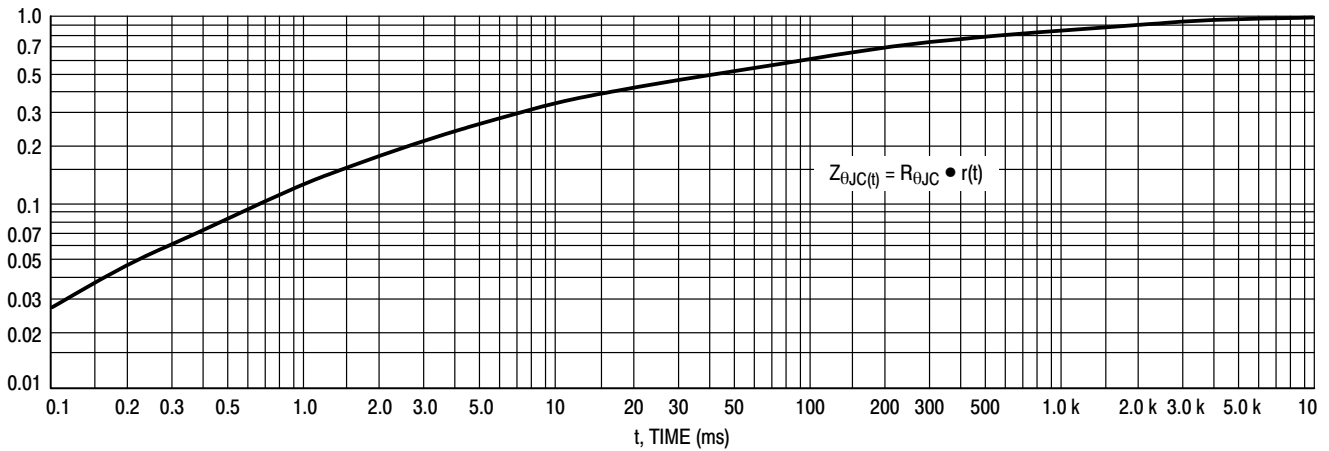


Figure 5. Thermal Response

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TYPICAL CHARACTERISTICS

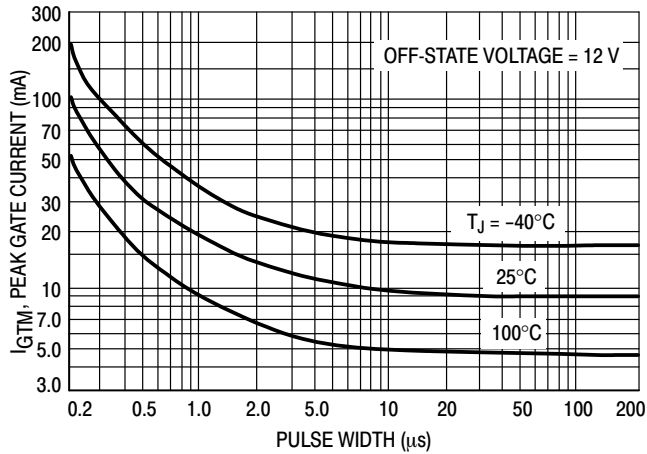


Figure 6. Typical Gate Trigger Current versus Pulse Width

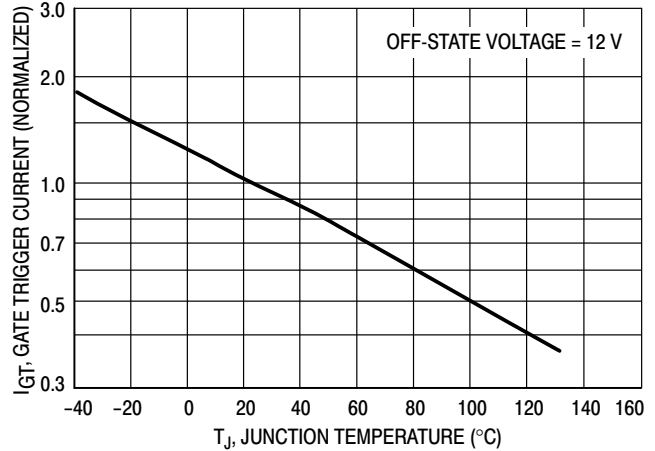


Figure 7. Typical Gate Trigger Current versus Temperature

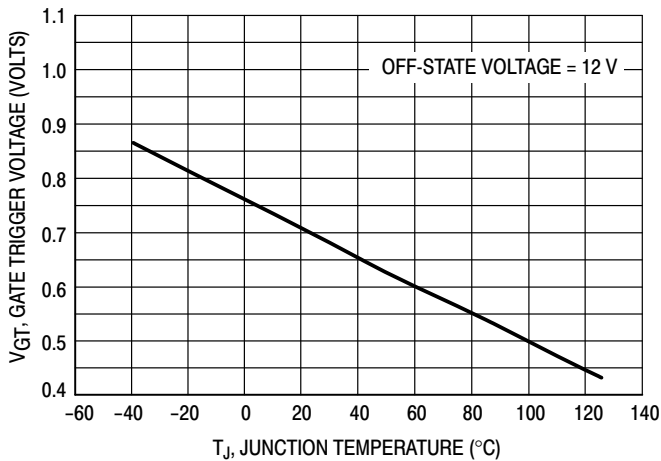


Figure 8. Typical Gate Trigger Voltage versus Temperature

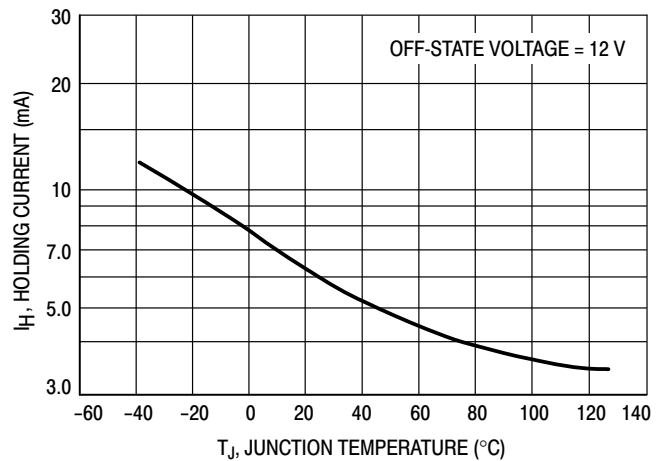


Figure 9. Typical Holding Current versus Temperature

ORDERING INFORMATION

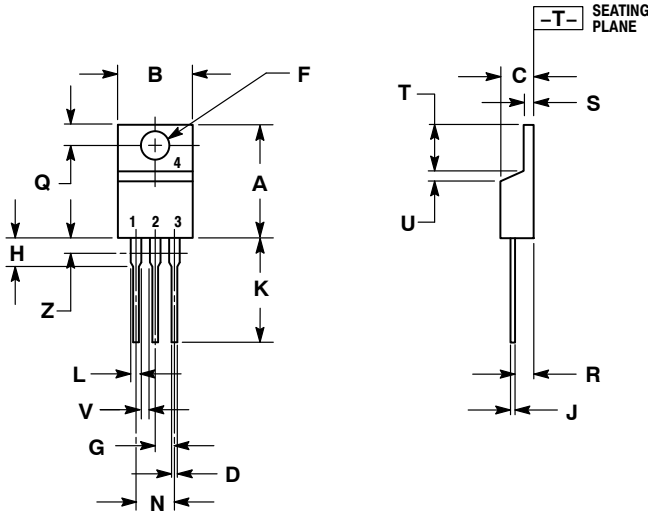
Device	Package	Shipping**
2N6394G	TO-220AB (Pb-Free)	500 Units / Bulk
2N6394TG		50 Units / Rail
2N6395G		500 Units / Bulk
2N6397G		500 Units / Bulk
2N6397TG		50 Units / Rail
2N6399G		500 Units / Bulk
2N6399TG		50 Units / Rail

**For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

2N6394 Series

PACKAGE DIMENSIONS

TO-220AB
CASE 221A-07
ISSUE AA



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
H	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

STYLE 3:

- PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

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